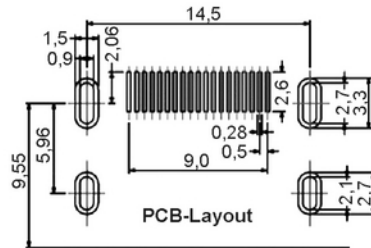
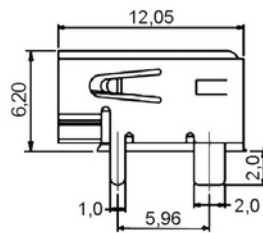
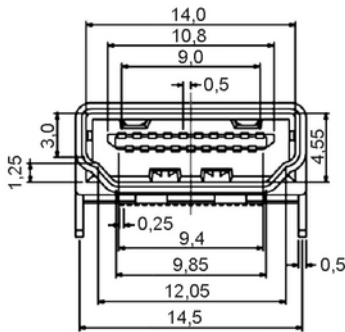
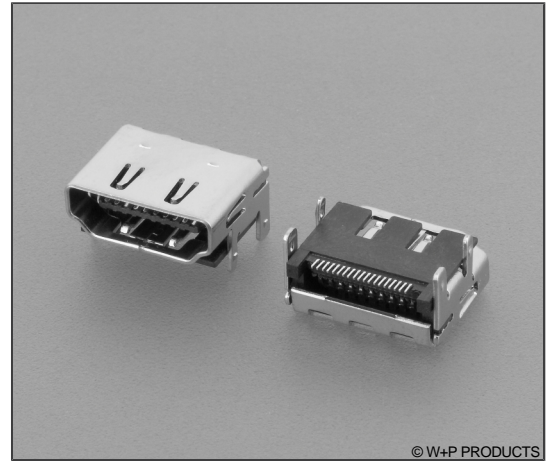


8800

SMT-HDMI Steckverbinder, Buchse liegend SMT HDMI Connectors, Jack Horizontal

Technische Daten / Technical Data

| | |
|--|---|
| Isolierkörper <i>Insulator</i> | Thermoplastischer Kunststoff, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i> |
| Kontaktmaterial <i>Contact Material</i> | Kupferlegierung <i>Copper alloy</i> |
| Durchgangswiderstand <i>Contact Resistance</i> | < 10mΩ <i>< 10mΩ</i> |
| Isolationswiderstand <i>Insulation Resistance</i> | > 100MΩ <i>> 100MΩ</i> |
| Spannungsfestigkeit <i>Test Voltage</i> | 500V _{AC} <i>500V_{AC}</i> |
| Nennstrom <i>Current Rating</i> | 0,5A <i>0.5A</i> |
| Temperaturbereich <i>Temperature Range</i> | -20°C ... +85°C <i>-20°C ... +85°C</i> |
| Verarbeitung <i>Processing</i> | Reflow-Lötverfahren <i>Reflow soldering</i> |



| | | | | |
|---------------|-----------------|--------------------|-------------------------|------------------------|
| Series | Contacts | Entry Type | Connector Type | Plating |
| 8800 | 19 | 2 | 2 | 70 |
| | | 2 Buchse Female | 2 Liegend Horizontal | 70 Sel. Au 0,38µm / Sn |

Informationen zum Reflow-Lötverfahren

Reflow Soldering Information

Reflow-Lötempfehlung

Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

| Profileigenschaft | Kennwert |
|--------------------------------------|--------------|
| Temperatur Minimum T_{Smin} | 150°C |
| Temperatur Maximum T_{Smax} | 200°C |
| Dauer $T_{Smin} - T_{Smax}$ | 60-180s |
| Temperatur Lötbereich T_L | 217°C |
| Verweildauer oberhalb T_L | 60-180s |
| Ramp-Up Rate $T_{Smax} - T_P$ | max. 3°C / s |
| Höchsttemperatur T_P | 260°C ±5 |
| Dauer Höchsttemperatur | 20-40s |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6°C / s |
| Dauer 25°C - Höchsttemperatur T_P | Max. 8 min |

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

| Profile Feature | Key Values |
|--------------------------------------|--------------|
| Minimum Temperature T_{Smin} | 150°C |
| Maximum Temperatur T_{Smax} | 200°C |
| Duration $T_{Smin} - T_{Smax}$ | 60-180s |
| Soldering Range Temperature T_L | 217°C |
| Duration above T_L | 60-180s |
| Ramp-Up Rate $T_{Smax} - T_P$ | max. 3°C / s |
| Peak Temperature T_P | 260°C ±5 |
| Duration Peak Temperature | 20-40s |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6°C / s |
| Duration 25°C - Peak Temp. T_P | Max. 8min |

